

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00449	1.33	0.04788
	Doped silicon	Silicon (Si)	7440-21-3	0.3328	98.67	3.55212
Subtotal				0.33729	100	3.6
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.03757	0.1	0.401
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01127	0.03	0.1203
	Copper alloy	Iron (Fe)	7439-89-6	0.03757	0.1	0.401
	Copper alloy	Copper (Cu)	7440-50-8	37.48295	99.77	400.0777
Subtotal				37.56936	100	401
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.84665	4.8	30.384
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	5.93053	10.0	63.3
	Filler	Silica fused	60676-86-0	50.40946	85.0	538.05
	Carbon Black	Carbon black	1333-86-4	0.11861	0.2	1.266
Subtotal				59.30525	100	633
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.34223	100.0	25
			Subtotal	2.34223	100	25
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.11796	100.0	1.25909
			Subtotal	0.11796	100	1.25909
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00656	2.0	0.07
		Silver (Ag)	7440-22-4	0.0082	2.5	0.0875
		Lead (Pb)	7439-92-1	0.31316	95.5	3.3425
Subtotal				0.32792	100	3.5
Total				100.00001	100	1067.35909

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